

MOSFET

OptiMOS™ Power-Transistor, -100 V

Features

- P-channel
- 100% avalanche tested
- Normal level
- Enhancement mode
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Fully qualified according to JEDEC for Industrial Applications

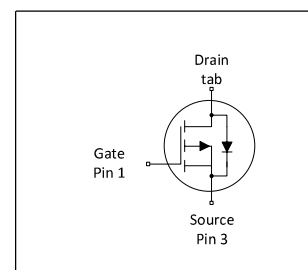
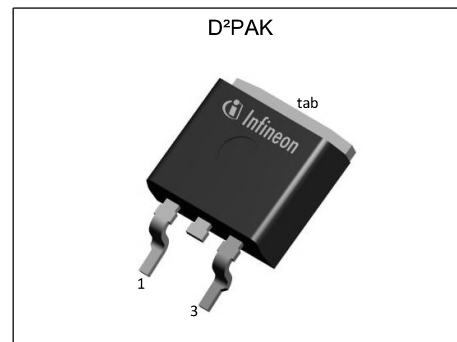


Table 1 Key Performance Parameters

| Parameter | Value | Unit |
|------------------|-------|------|
| V_{DS} | -100 | V |
| $R_{DS(on),max}$ | 33 | mΩ |
| I_D | -62 | A |
| Q_{oss} | -66 | nC |
| Q_G | -189 | nC |



RoHS

| Type / Ordering Code | Package | Marking | Related Links |
|----------------------|------------|----------|---------------|
| IPB330P10NM | PG-TO263-3 | 330P10NM | - |

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1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|-------------------|--------|------|--------------------|------|--|
| | | Min. | Typ. | Max. | | |
| Continuous drain current ¹⁾ | I_D | - | - | -62 -44 -6.9 | A | $V_{GS}=-10\text{ V}$, $T_C=25\text{ °C}$ $V_{GS}=-10\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=-10\text{ V}$, $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^{2)}$ |
| Pulsed drain current ³⁾ | $I_{D,pulse}$ | - | - | -248 | A | $T_A=25\text{ °C}$ |
| Avalanche energy, single pulse ⁴⁾ | E_{AS} | - | - | 1960 | mJ | $I_D=-53\text{ A}$, $R_{GS}=25\text{ }\Omega$ |
| Gate source voltage | V_{GS} | -20 | - | 20 | V | - |
| Power dissipation | P_{tot} | - | - | 300 3.8 | W | $T_C=25\text{ °C}$ $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^{2)}$ |
| Operating and storage temperature | T_j , T_{stg} | -55 | - | 175 | °C | IEC climatic category; DIN IEC 68-1: 55/175/56 |

2 Thermal characteristics

Table 3 Thermal characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---|------------|--------|------|------|------|-----------------------|
| | | Min. | Typ. | Max. | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | 0.5 | °C/W | - |
| Thermal resistance, junction - ambient, 6 cm ² cooling area | R_{thJA} | - | - | 40 | °C/W | - |
| Thermal resistance, junction - ambient, minimal footprint ²⁾ | R_{thJA} | - | - | 62 | °C/W | - |

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See Diagram 3 for more detailed information

⁴⁾ See Diagram 13 for more detailed information

3 Electrical characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|----------------------------------|---------------|--------|-------------|------------|---------------|---|
| | | Min. | Typ. | Max. | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | -100 | - | - | V | $V_{GS}=0\text{ V}$, $I_D=-1\text{ mA}$ |
| Gate threshold voltage | $V_{GS(th)}$ | -2.1 | -3 | -4 | V | $V_{DS}=V_{GS}$, $I_D=-5550\text{ }\mu\text{A}$ |
| Zero gate voltage drain current | I_{DSS} | - | -0.1 -10 | -1 -100 | μA | $V_{DS}=-100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=-100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$ |
| Gate-source leakage current | I_{GSS} | - | -10 | -100 | nA | $V_{GS}=-20\text{ V}$, $V_{DS}=0\text{ V}$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 26.8 | 33 | m Ω | $V_{GS}=-10\text{ V}$, $I_D=-53\text{ A}$ |
| Gate resistance | R_G | - | 5.4 | - | Ω | - |
| Transconductance | g_{fs} | - | 75 | - | S | $ V_{DS} \geq 2 I_D /R_{DS(on)max}$, $I_D=-53\text{ A}$ |

Table 5 Dynamic characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|--------------|--------|--------|-------|------|---|
| | | Min. | Typ. | Max. | | |
| Input capacitance ¹⁾ | C_{iss} | - | 8200 | 11000 | pF | $V_{GS}=0\text{ V}$, $V_{DS}=-50\text{ V}$, $f=1\text{ MHz}$ |
| Output capacitance ¹⁾ | C_{oss} | - | 580 | 750 | pF | $V_{GS}=0\text{ V}$, $V_{DS}=-50\text{ V}$, $f=1\text{ MHz}$ |
| Reverse transfer capacitance ¹⁾ | C_{rss} | - | 110 | 190 | pF | $V_{GS}=0\text{ V}$, $V_{DS}=-50\text{ V}$, $f=1\text{ MHz}$ |
| Turn-on delay time | $t_{d(on)}$ | - | 13.08 | - | ns | $V_{DD}=-50\text{ V}$, $V_{GS}=-10\text{ V}$, $I_D=-53\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time | t_r | - | 51.1 | - | ns | $V_{DD}=-50\text{ V}$, $V_{GS}=-10\text{ V}$, $I_D=-53\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time | $t_{d(off)}$ | - | 177.95 | - | ns | $V_{DD}=-50\text{ V}$, $V_{GS}=-10\text{ V}$, $I_D=-53\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time | t_f | - | 81.95 | - | ns | $V_{DD}=-50\text{ V}$, $V_{GS}=-10\text{ V}$, $I_D=-53\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |

Table 6 Gate charge characteristics²⁾

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|------------------------------------|---------------|--------|------|------|------|--|
| | | Min. | Typ. | Max. | | |
| Gate to source charge | Q_{gs} | - | -39 | - | nC | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Gate charge at threshold | $Q_{g(th)}$ | - | -25 | - | nC | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Gate to drain charge ¹⁾ | Q_{gd} | - | -59 | -89 | nC | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Switching charge | Q_{sw} | - | -74 | - | nC | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Gate charge total ¹⁾ | Q_g | - | -189 | -236 | nC | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Gate plateau voltage | $V_{plateau}$ | - | -4.8 | - | V | $V_{DD}=-50\text{ V}$, $I_D=-53\text{ A}$, $V_{GS}=0\text{ to }-10\text{ V}$ |
| Output charge ¹⁾ | Q_{oss} | - | -66 | -88 | nC | $V_{DS}=-50\text{ V}$, $V_{GS}=0\text{ V}$ |

¹⁾ Defined by design. Not subject to production test.

²⁾ See "Gate charge waveforms" for parameter definition

Table 7 Reverse diode

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---------------------------------------|---------------|--------|--------|--------|------|---|
| | | Min. | Typ. | Max. | | |
| Diode continuous forward current | I_S | - | - | -62 | A | $T_C=25\text{ °C}$ |
| Diode pulse current | $I_{S,pulse}$ | - | - | -248 | A | $T_C=25\text{ °C}$ |
| Diode forward voltage | V_{SD} | - | -0.86 | -1.2 | V | $V_{GS}=0\text{ V}$, $I_F=-53\text{ A}$, $T_j=25\text{ °C}$ |
| Reverse recovery time ¹⁾ | t_{rr} | - | 110 | 220 | ns | $V_R=-50\text{ V}$, $I_F=-53\text{ A}$, $di_F/dt=-100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge ¹⁾ | Q_{rr} | - | 588.56 | 1177.1 | nC | $V_R=-50\text{ V}$, $I_F=-53\text{ A}$, $di_F/dt=-100\text{ A}/\mu\text{s}$ |

¹⁾ Defined by design. Not subject to production test.

4 Electrical characteristics diagrams

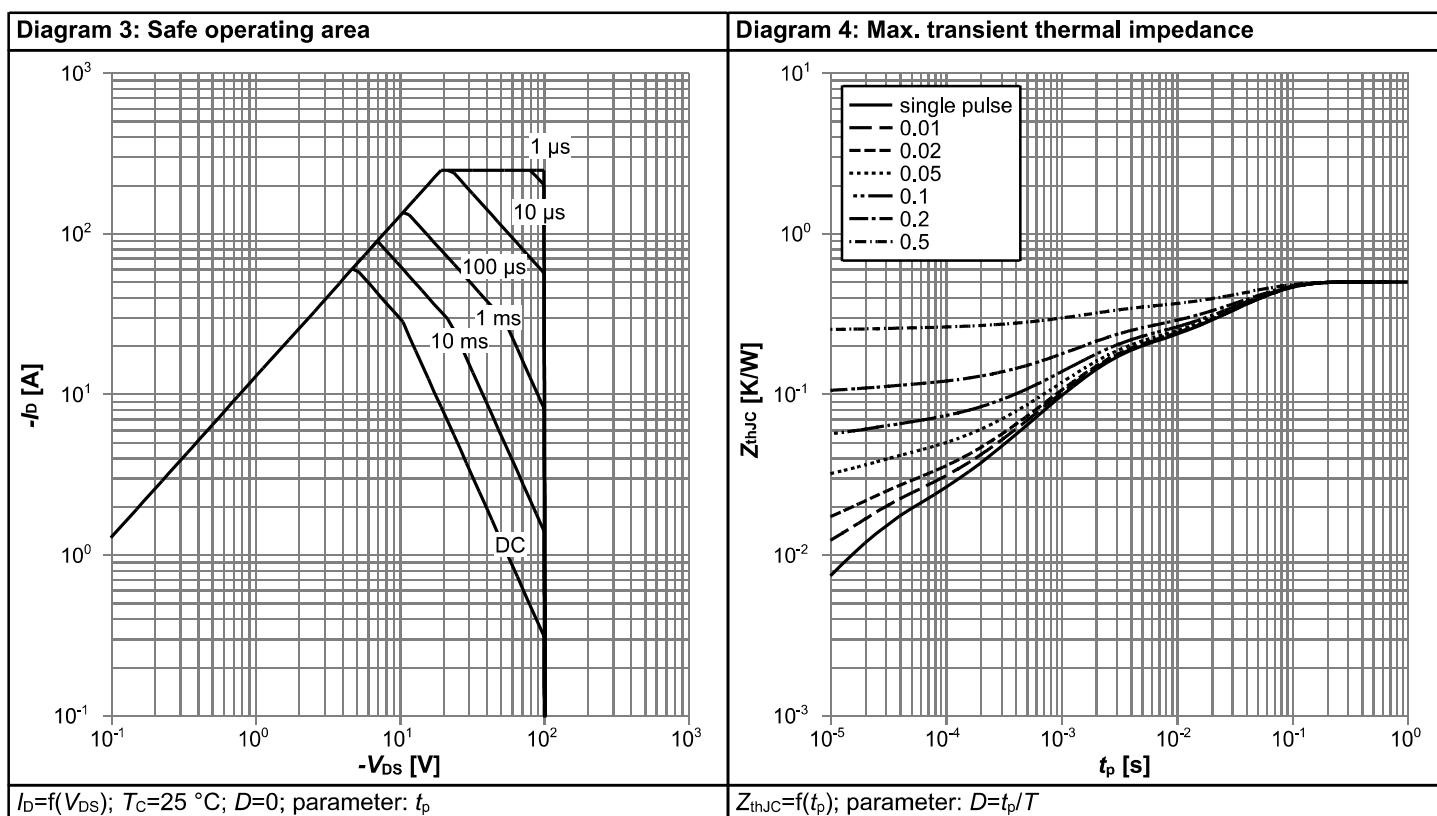
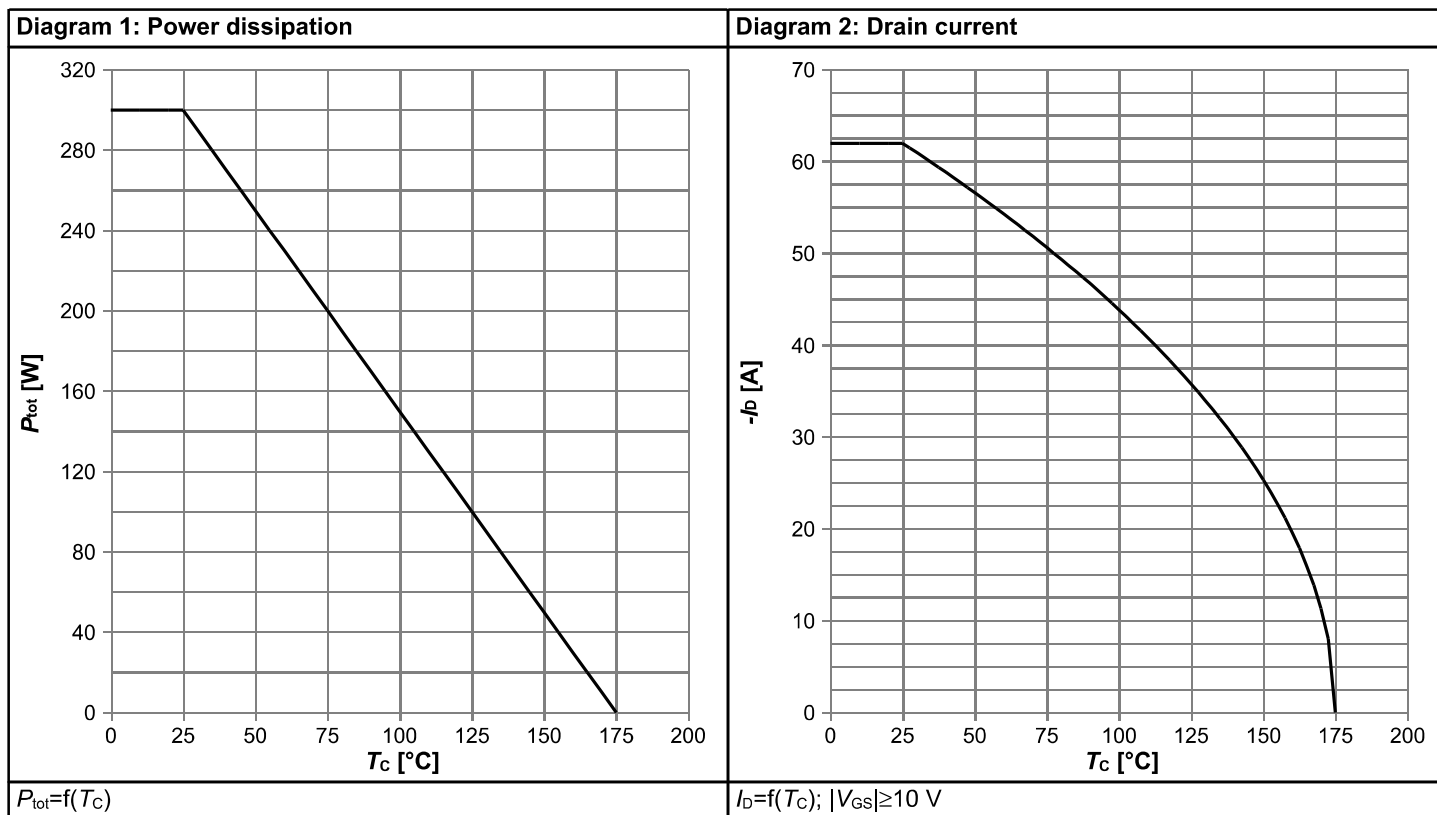
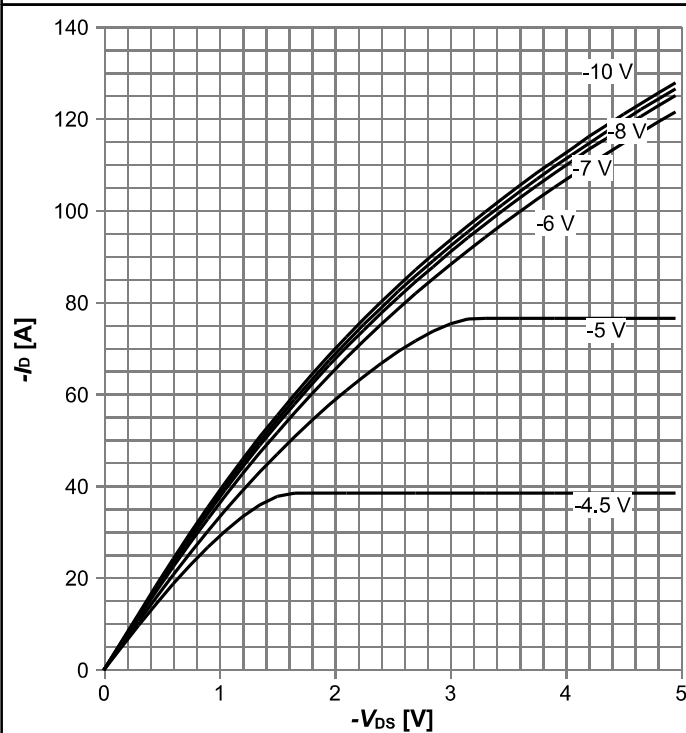
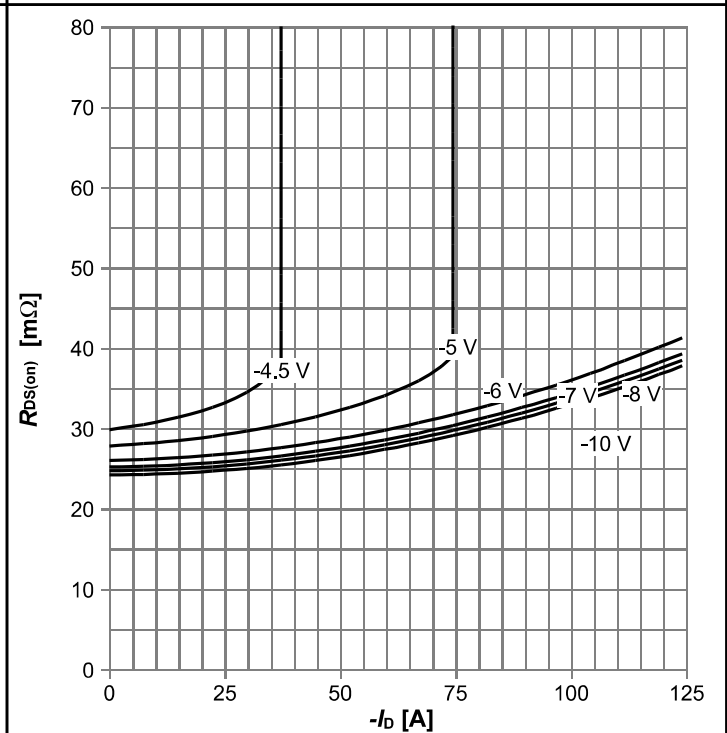


Diagram 5: Typ. output characteristics



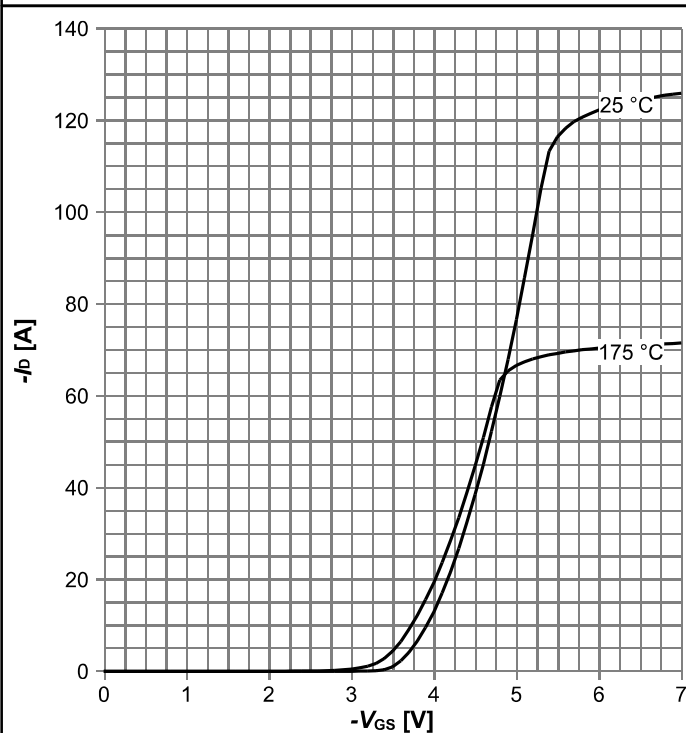
$I_D = f(V_{DS})$, $T_j = 25^\circ\text{C}$; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



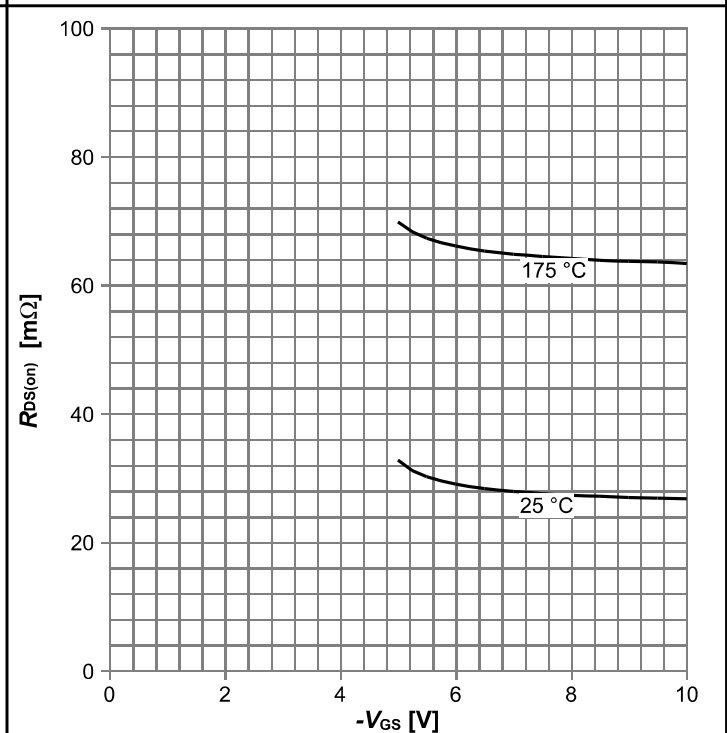
$R_{DS(on)} = f(I_D)$, $T_j = 25^\circ\text{C}$; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



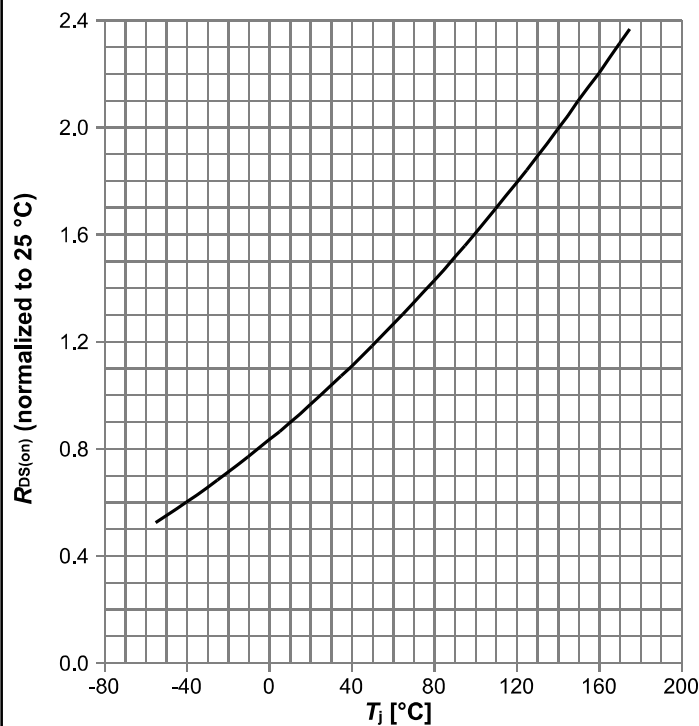
$I_D = f(V_{GS})$, $|V_{DS}| > 2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



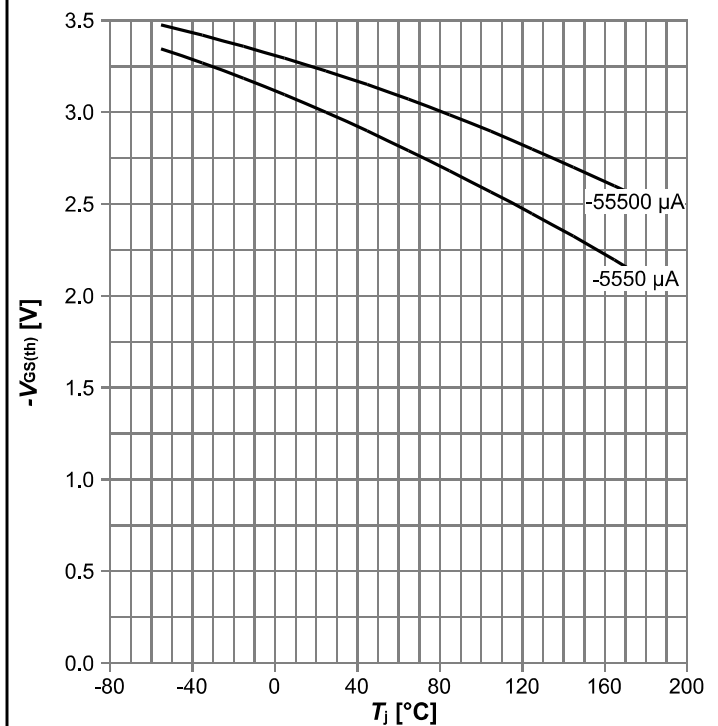
$R_{DS(on)} = f(V_{GS})$, $I_D = -53$ A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



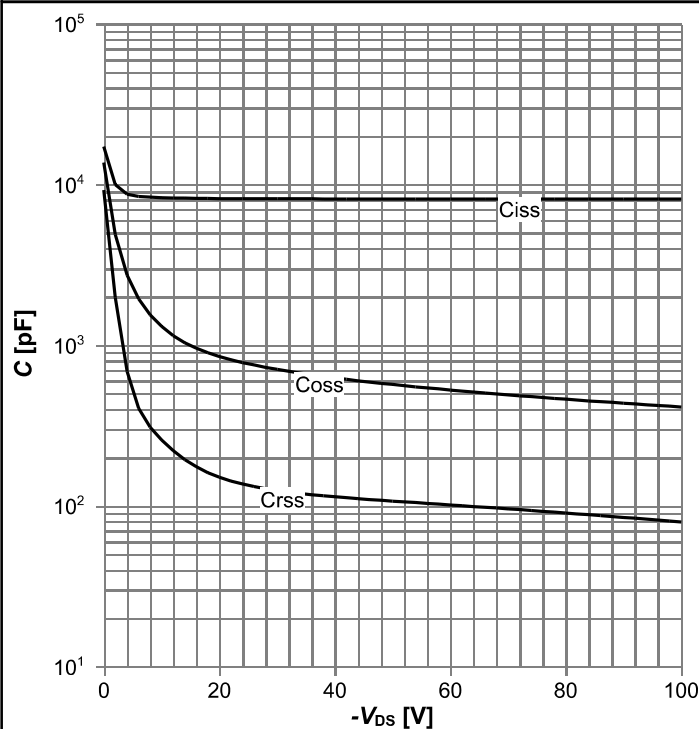
$R_{DS(on)} = f(T_j)$, $I_D = -53$ A, $V_{GS} = -10$ V

Diagram 10: Typ. gate threshold voltage



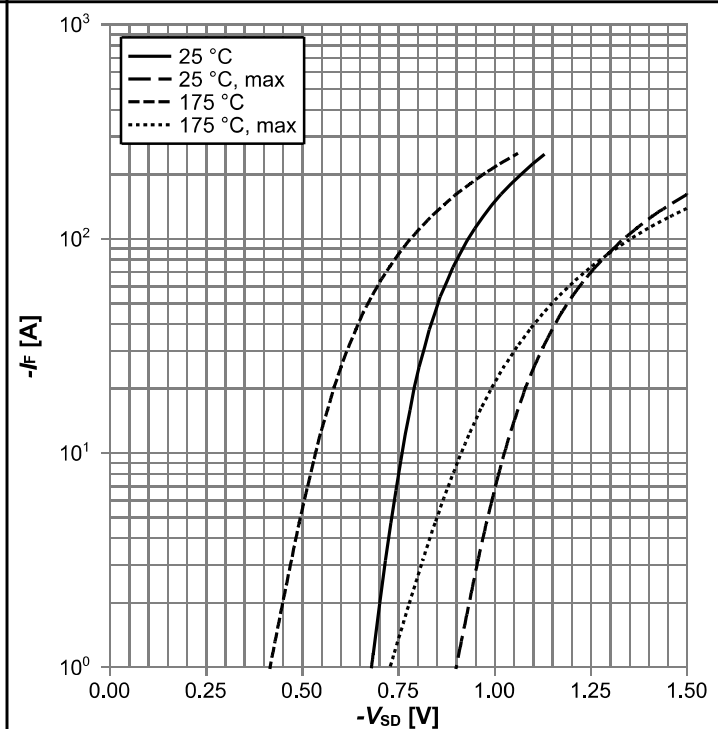
$V_{GS(th)} = f(T_j)$, $V_{GS} = V_{DS}$; parameter: I_D

Diagram 11: Typ. capacitances



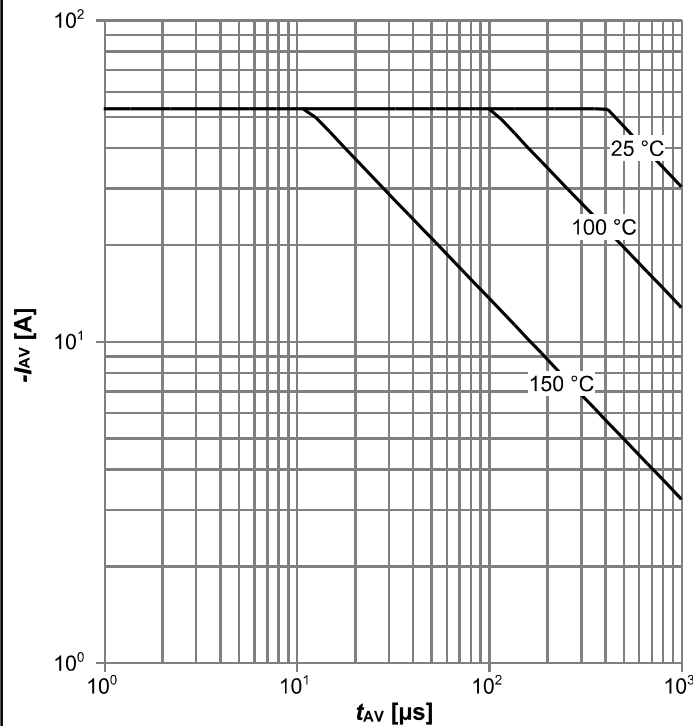
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz

Diagram 12: Forward characteristics of reverse diode



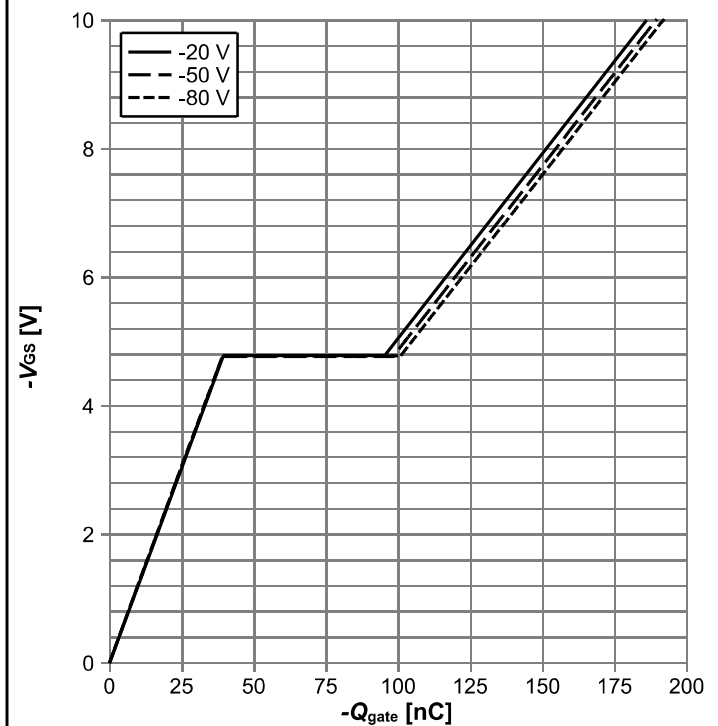
$I_F = f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



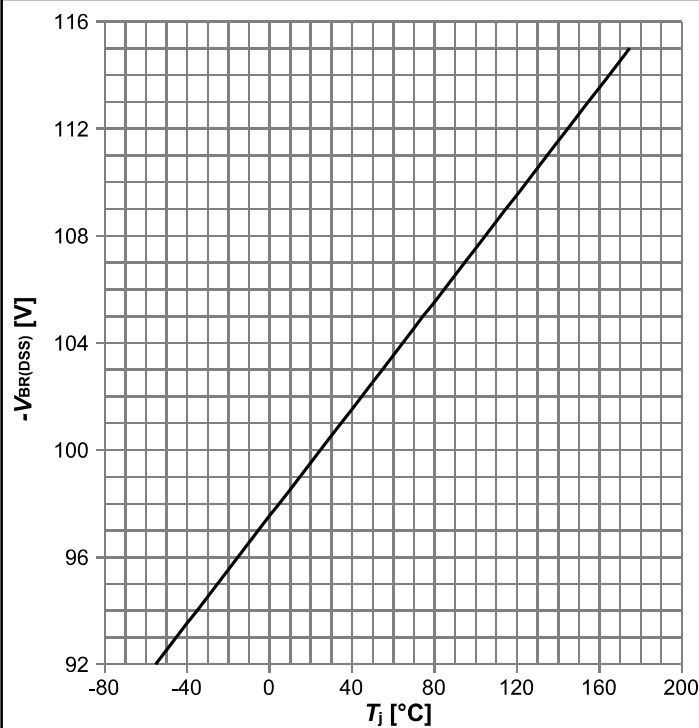
$I_{AS}=f(t_{AV})$; $R_{GS}=25\ \Omega$; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



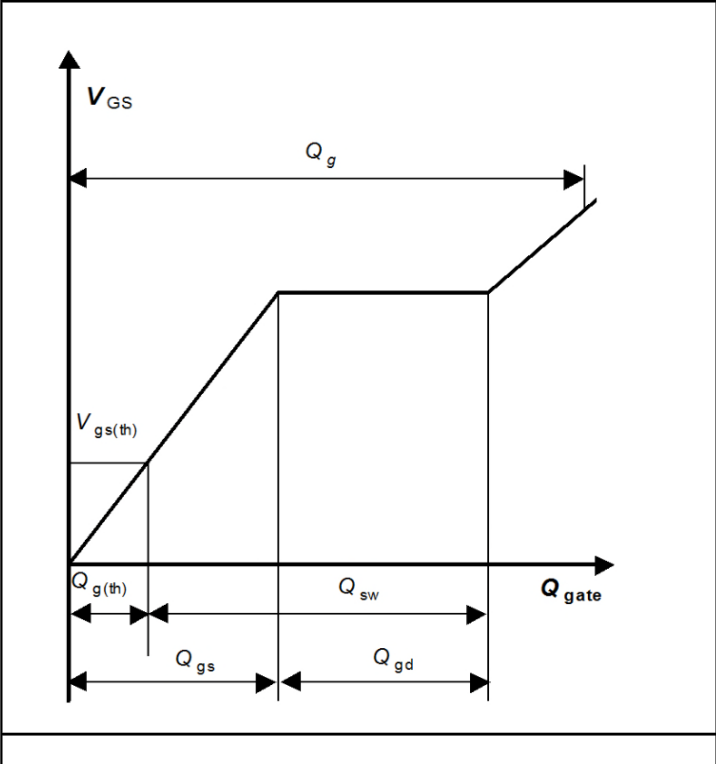
$V_{GS}=f(Q_{gate})$, $I_D=-53\text{ A}$ pulsed, $T_j=25\text{ °C}$; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage



$V_{BR(DSS)}=f(T_j)$; $I_D=-1\text{ mA}$

Diagram Gate charge waveforms



5 Package Outlines

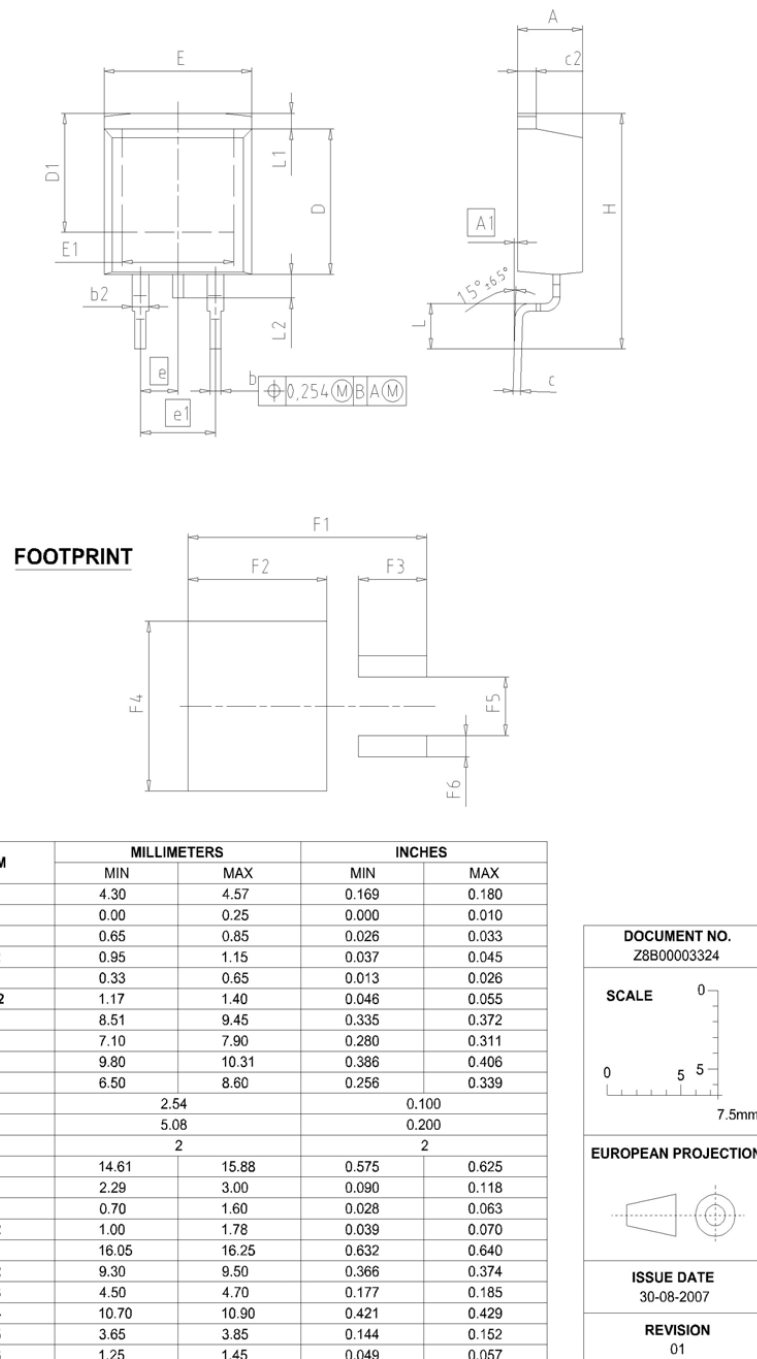


Figure 1 Outline PG-TO263-3, dimensions in mm/inches

Revision History

IPB330P10NM

Revision: 2021-05-24, Rev. 2.0

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.0 | 2021-05-24 | Release of final version |

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